



NSAI
Standards

Irish Standard
I.S. EN IEC 61188-6-4:2019

Printed boards and printed board assemblies - Design and use - Part 6-4: Land pattern design - Generic requirements for dimensional drawings of surface mounted components (SMD) from the viewpoint of land pattern design

I.S. EN IEC 61188-6-4:2019

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NSAI
1 Swift Square,
Northwood, Santry
Dublin 9

T +353 1 807 3800
F +353 1 807 3838
E standards@nsai.ie
W NSAI.ie

Sales:
T +353 1 857 6730
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National Foreword

I.S. EN IEC 61188-6-4:2019 is the adopted Irish version of the European Document EN IEC 61188-6-4:2019, Printed boards and printed board assemblies - Design and use - Part 6-4: Land pattern design - Generic requirements for dimensional drawings of surface mounted components (SMD) from the viewpoint of land pattern design

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EUROPEAN STANDARD

EN 61188-6-4

NORME EUROPÉENNE

EUROPÄISCHE NORM

July 2019

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English Version

Printed boards and printed board assemblies - Design and use -
Part 6-4: Land pattern design - Generic requirements for
dimensional drawings of surface mounted components (SMD)
from the viewpoint of land pattern design
(IEC 61188-6-4:2019)

Cartes imprimées et cartes imprimées équipées -
Conception et utilisation - Partie 6-4: Conception de la zone
de report - Exigences génériques pour les dessins
dimensionnels de composants montés en surface (CMS) du
point de vue de la conception de la zone de report
(IEC 61188-6-4:2019)

Leiterplatten und Flachbaugruppen - Konstruktion und
Anwendung - Teil 6-4: Allgemeine Anforderungen an SMD-
Maßzeichnungen hinsichtlich der Konstruktion des
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Europäisches Komitee für Elektrotechnische Normung

CEN-CENELEC Management Centre: Rue de la Science 23, B-1040 Brussels

EN 61188-6-4:2019 (E)**European foreword**

The text of document 91/1561/FDIS, future edition 1 of IEC 61188-6-4, prepared by IEC/TC 91 "Electronics assembly technology" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN 61188-6-4:2019.

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- latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2020-03-06
- latest date by which the national standards conflicting with the document have to be withdrawn (dow) 2022-06-06

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IEC 60191-1	NOTE	Harmonized as EN IEC 60191-1
IEC 60191-6	NOTE	Harmonized as EN 60191-6
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IEC 61188-5-1	NOTE	Harmonized as EN 61188-5-1
IEC 61188-5-2	NOTE	Harmonized as EN 61188-5-2
IEC 61188-5-3	NOTE	Harmonized as EN 61188-5-3
IEC 61188-5-4	NOTE	Harmonized as EN 61188-5-4
IEC 61188-5-5	NOTE	Harmonized as EN 61188-5-5
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IEC 61188-5-8	NOTE	Harmonized as EN 61188-5-8
IEC 61191-1	NOTE	Harmonized as EN IEC 61191-1
IEC 61191-2	NOTE	Harmonized as EN 61191-2

Normative references to international publications with their corresponding European publications

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NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cenelec.eu.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60194	-	Terms and definitions for printed circuits	-	-
IEC 60194-2	-	Printed boards design, manufacture and assembly - Vocabulary - Part 2: Common usage in electronic technologies as well as printed board and electronic assembly technologies	-	-

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IEC 61188-6-4

Edition 1.0 2019-05

INTERNATIONAL STANDARD

NORME INTERNATIONALE



**Printed boards and printed board assemblies – Design and use –
Part 6-4: Land pattern design – Generic requirements for dimensional drawings
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**Cartes imprimées et cartes imprimées équipées – Conception et utilisation –
Partie 6-4: Conception de la zone de report – Exigences génériques pour les
dessins dimensionnels de composants montés en surface (CMS) du point
de vue de la conception de la zone de report**





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IEC Central Office
3, rue de Varembe
CH-1211 Geneva 20
Switzerland

Tel.: +41 22 919 02 11
info@iec.ch
www.iec.ch

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IEC 61188-6-4

Edition 1.0 2019-05

INTERNATIONAL STANDARD

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dessins dimensionnels de composants montés en surface (CMS) du point
de vue de la conception de la zone de report**

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

**PRINTED BOARDS AND PRINTED BOARD ASSEMBLIES –
DESIGN AND USE –**
**Part 6-4: Land pattern design – Generic requirements for dimensional
drawings of surface mounted components (SMD) from the viewpoint of
land pattern design**

FOREWORD

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International Standard IEC 61188-6-4 has been prepared by IEC technical committee 91: Electronics assembly technology.

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FDIS	Report on voting
91/1561/FDIS	91/1572/RVD

Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 61188 series, published under the general title *Printed boards and printed board assemblies – Design and use*, can be found on the IEC website.

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PRINTED BOARDS AND PRINTED BOARD ASSEMBLIES – DESIGN AND USE –

Part 6-4: Land pattern design – Generic requirements for dimensional drawings of surface mounted components (SMD) from the viewpoint of land pattern design

1 Scope

This part of IEC 61188 specifies generic requirements for dimensional drawings of SMD from the viewpoint of land pattern design.

The purpose of this document is to prevent land pattern design issues caused by lack of information and/or misuse of the information from SMD outline drawing as well as to improve the utilization of IEC 61188 series.

This document is applicable to the SMD of semiconductor devices and electrical components.

2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60194, *Printed board design, manufacture and assembly – Terms and definitions*

IEC 60194-2, *Printed board design, manufacture and assembly – Vocabulary – Part 2: Common usage in electronic technologies as well as printed board and electronic assembly technologies*

3 Terms, definitions and symbols

For the purposes of this document, the terms and definitions given in IEC 60194 and IEC 60194-2 apply, and the reference symbols are shown in Table 1.

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